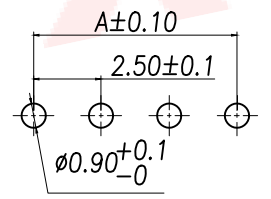
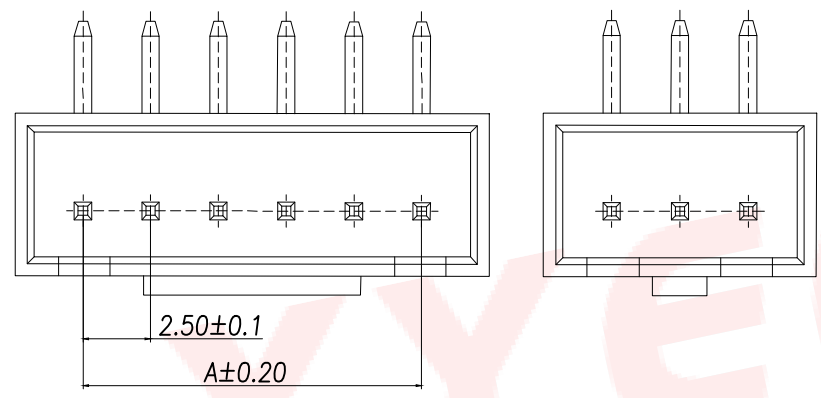
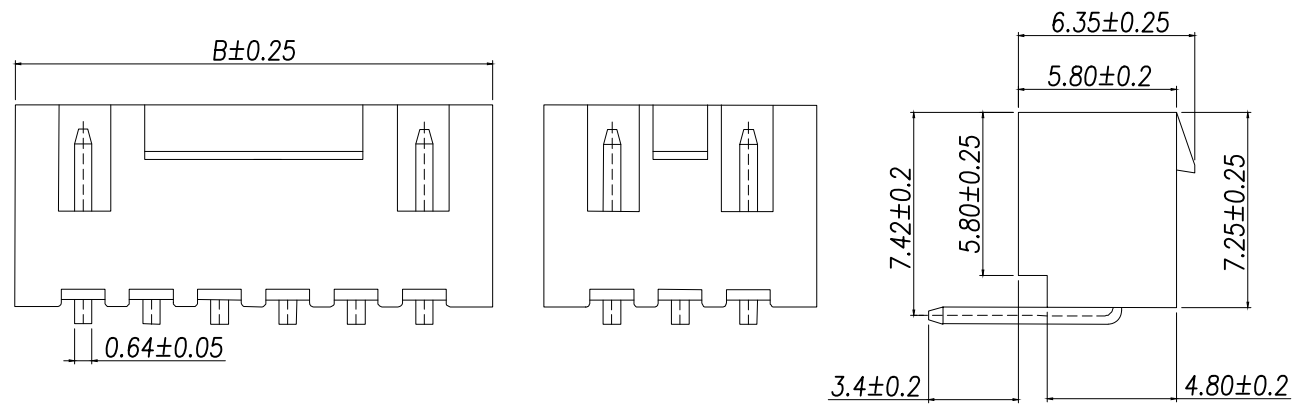


REV.	Q'TY	ECN. NO.	APR.	DATE



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim +85^{\circ}$
9. 可焊性试验: 浸锡面积 >95% 温度 235 , 时间 2.5±0.5秒
10. 铅和铜等六大有害物质含量要符合环保要求.

Part No	Pin	A	B
XY-XHB-2AW-CJ	2	2.50	7.50
XY-XHB-3AW-CJ	3	5.00	10.00
XY-XHB-4AW-CJ	4	7.50	12.50
XY-XHB-5AW-CJ	5	10.00	15.00
XY-XHB-6AW-CJ	6	12.50	17.50
XY-XHB-7AW-CJ	7	15.00	20.00
XY-XHB-8AW-CJ	8	17.50	22.50
XY-XHB-9AW-CJ	9	20.00	25.00
XY-XHB-10AW-CJ	10	22.50	27.50
XY-XHB-11AW-CJ	11	25.00	30.00
XY-XHB-12AW-CJ	12	27.50	32.50
XY-XHB-13AW-CJ	13	30.00	35.00
XY-XHB-14AW-CJ	14	32.50	37.50
XY-XHB-15AW-CJ	15	35.00	40.00
XY-XHB-16AW-CJ	16	37.50	42.50
XY-XHB-17AW-CJ	17	40.00	45.00
XY-XHB-18AW-CJ	18	42.50	47.50
XY-XHB-19AW-CJ	19	45.00	50.00
XY-XHB-20AW-CJ	20	47.50	52.50

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.35	X.*±5°	APR.	Alex	TITLE: WAFER HA2.54MM 带扣 弯针	
.XX±0.25	.X*±3°	CHK.	Jack	DWG NO. XY-XHB-NAW-CJ	
.XXX±0.15	.XX*±1°	DRA.	Can	PROJ. CUSTOMER DRAWING	
		SIZE A4	SCALE 1:1	SHEET 1/1	REV. A